



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Kazuto NISHIDA et al.

: Docket No.2001_1055A

Serial No. 09/890,066

: Group Art Unit 1734

Filed July 26, 2001

ELECTRONIC COMPONENT MOUNTING
METHOD AND APPARATUS

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEE FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975.

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents,
Washington, D.C.

Sir:

Kindly amend the application as follows:

IN THE CLAIMS:

Kindly amend claim 46 as follows:

46.(Amended) An electronic component mounting method comprising:
mounting an electronic component (1) on a circuit board (4)
while aligning in position an electrode of the electronic component (1) and an electrode
(5) of the circuit board (4) in a state in which the electrode (2) of the electronic component
(1) has a bump (3, 103) with interposition of an anisotropic conductive layer (10) in which
an insulating resin mixed with an inorganic filler is mixed with a conductive particle (10a);
and

subsequently bonding the electronic component to the circuit
board by hardening the insulating resin of the anisotropic conductive layer interposed
between the electronic component and the circuit board while correcting warp of the board

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